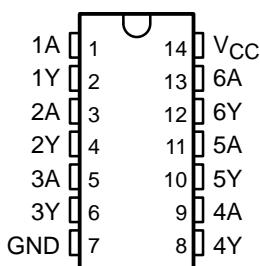
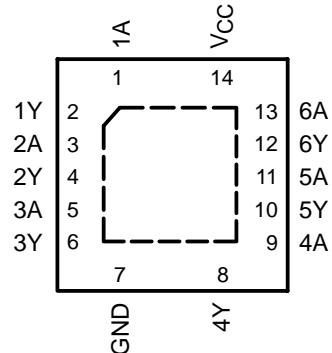


- Operating Range 2-V to 5.5-V V_{CC}
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

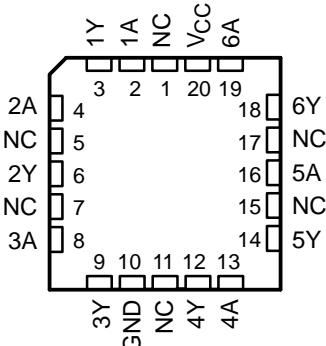
**SN54AHC14 . . . J OR W PACKAGE
SN74AHC14 . . . D, DB, DGV, N, NS,
OR PW PACKAGE
(TOP VIEW)**



**SN74AHC14 . . . RGY PACKAGE
(TOP VIEW)**



**SN54AHC14 . . . FK PACKAGE
(TOP VIEW)**



NC – No internal connection

description/ordering information

The 'AHC14 devices contain six independent inverters. These devices perform the Boolean function $Y = \bar{A}$.

Each circuit functions as an independent inverter, but because of the Schmitt action, the inverters have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74AHC14RGYR	HA14
	PDIP – N	Tube	SN74AHC14N	SN74AHC14N
	SOIC – D	Tube	SN74AHC14D	AHC14
		Tape and reel	SN74AHC14DR	
	SOP – NS	Tape and reel	SN74AHC14NSR	AHC14
	SSOP – DB	Tape and reel	SN74AHC14DBR	HA14
	TSSOP – PW	Tube	SN74AHC14PW	HA14
		Tape and reel	SN74AHC14PWR	
–55°C to 125°C	TVSOP – DGV	Tape and reel	SN74AHC14DGVR	HA14
	CDIP – J	Tube	SNJ54AHC14J	SNJ54AHC14J
	CFP – W	Tube	SNJ54AHC14W	SNJ54AHC14W
	LCCC – FK	Tube	SNJ54AHC14FK	SNJ54AHC14FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

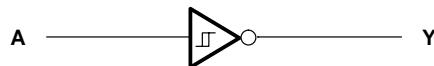
SN54AHC14, SN74AHC14 HEX SCHMITT-TRIGGER INVERTERS

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FUNCTION TABLE
(each inverter)

INPUT A	OUTPUT Y
H	L
L	H

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	-0.5 V to 7 V
Input voltage range, V _I (see Note 1)	-0.5 V to 7 V
Output voltage range, V _O (see Note 1)	-0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	-20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±20 mA
Continuous output current, I _O (V _O = 0 to V _{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 2): D package	86°C/W
(see Note 2): DB package	96°C/W
(see Note 2): DGV package	127°C/W
(see Note 2): N package	80°C/W
(see Note 2): NS package	76°C/W
(see Note 2): PW package	113°C/W
(see Note 3): RGY package	47°C/W
Storage temperature range, T _{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.
3. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 4)

		SN54AHC14		SN74AHC14		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	2	5.5	2	5.5	V
V _I	Input voltage	0	5.5	0	5.5	V
V _O	Output voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2 V		-50	-50	µA
		V _{CC} = 3.3 V ± 0.3 V		-4	-4	mA
		V _{CC} = 5 V ± 0.5 V		-8	-8	
I _{OL}	Low-level output current	V _{CC} = 2 V		50	50	µA
		V _{CC} = 3.3 V ± 0.3 V		4	4	mA
		V _{CC} = 5 V ± 0.5 V		8	8	
T _A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHC14		SN74AHC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{T+} Positive-going input threshold voltage		3 V	1.2	2.2	1.2	2.2	1.2	2.2	1.2	V
		4.5 V	1.75	3.15	1.75	3.15	1.75	3.15	1.75	
		5.5 V	2.15	3.85	2.15	3.85	2.15	3.85	2.15	
V _{T-} Negative-going input threshold voltage		3 V	0.9	1.9	0.9	1.9	0.9	1.9	0.9	V
		4.5 V	1.35	2.75	1.35	2.75	1.35	2.75	1.35	
		5.5 V	1.65	3.35	1.65	3.35	1.65	3.35	1.65	
ΔV_T Hysteresis ($V_{T+} - V_{T-}$)		3 V	0.3	1.2	0.3	1.2	0.3	1.2	0.3	V
		4.5 V	0.4	1.4	0.4	1.4	0.4	1.4	0.4	
		5.5 V	0.5	1.6	0.5	1.6	0.5	1.6	0.5	
V _{OH}	I _{OH} = -50 μ A	2 V	1.9	2	1.9		1.9		1.9	V
		3 V	2.9	3	2.9		2.9		2.9	
		4.5 V	4.4	4.5	4.4		4.4		4.4	
	I _{OH} = -4 mA	3 V	2.58		2.48		2.48		2.48	
	I _{OH} = -8 mA	4.5 V	3.94		3.8		3.8		3.8	
V _{OL}	I _{OL} = 50 μ A	2 V		0.1	0.1		0.1		0.1	V
		3 V		0.1	0.1		0.1		0.1	
		4.5 V		0.1	0.1		0.1		0.1	
	I _{OL} = 4 mA	3 V		0.36	0.5		0.44		0.44	
	I _{OL} = 8 mA	4.5 V		0.36	0.5		0.44		0.44	
I _I	V _I = 5.5 V or GND	0 V to 5.5 V		± 0.1	$\pm 1^*$		± 1		μ A	
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V		2	20		20		μ A	
C _i	V _I = V _{CC} or GND	5 V		2	10			10	pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

**switching characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHC14		SN74AHC14		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF	8.3**	12.8**	1**	15**	1	15	ns	ns
				8.3**	12.8**	1**	15**	1	15	ns	
t _{PLH}	A	Y	C _L = 50 pF	10.8	16.3	1	18.5	1	18.5	ns	ns
				10.8	16.3	1	18.5	1	18.5	ns	

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

**switching characteristics over recommended operating free-air temperature range,
V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHC14		SN74AHC14		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF	5.5**	8.6**	1**	10**	1	10	ns	ns
				5.5**	8.6**	1**	10**	1	10	ns	
t _{PLH}	A	Y	C _L = 50 pF	7	10.6	1	12	1	12	ns	ns
				7	10.6	1	12	1	12	ns	

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

SN54AHC14, SN74AHC14 HEX SCHMITT-TRIGGER INVERTERS

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noise characteristics, $V_{CC} = 5 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 5)

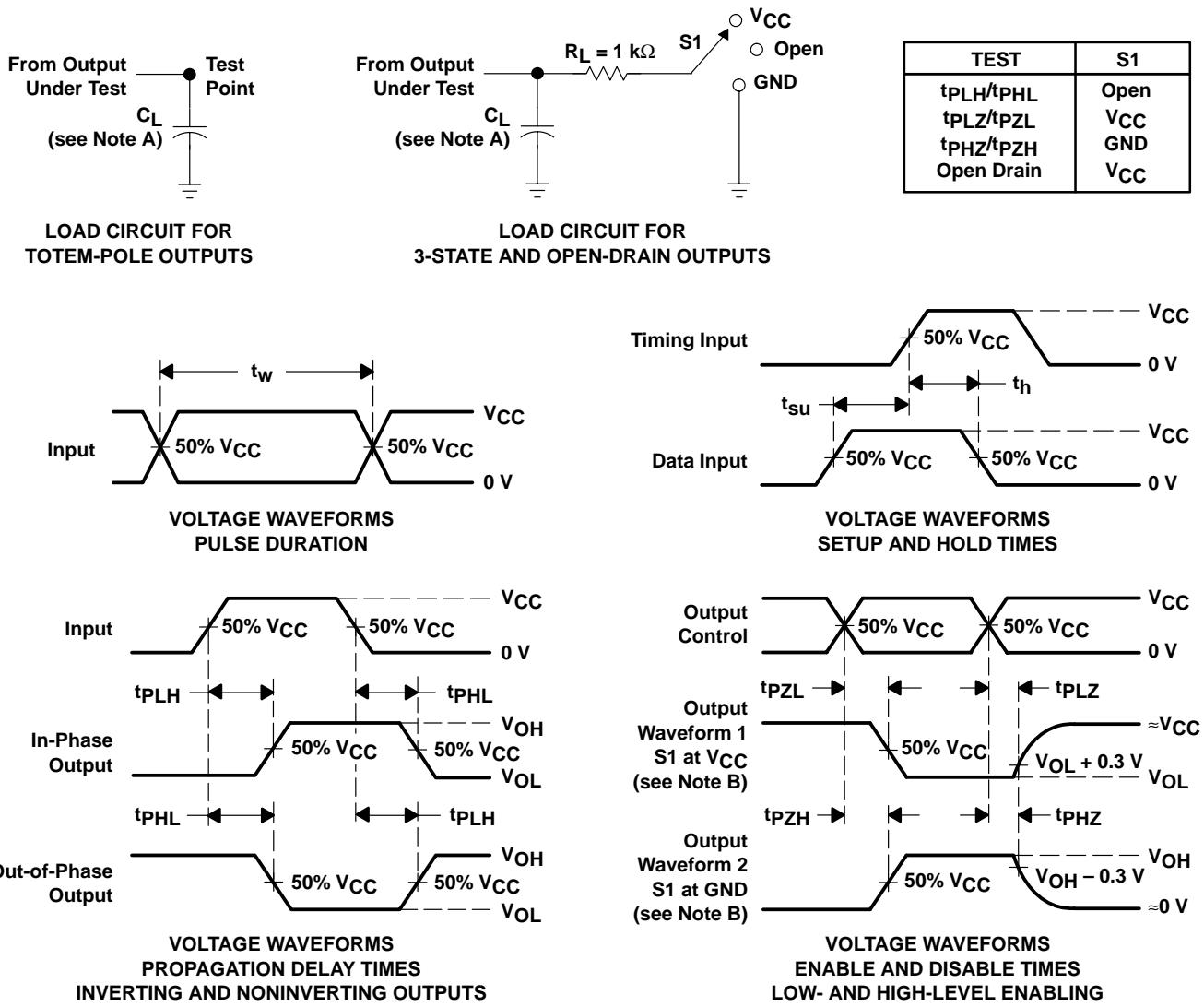
PARAMETER	SN74AHC14			UNIT
	MIN	TYP	MAX	
$V_{OL(P)}$ Quiet output, maximum dynamic V_{OL}		0.8		V
$V_{OL(V)}$ Quiet output, minimum dynamic V_{OL}		-0.4		V
$V_{OH(V)}$ Quiet output, minimum dynamic V_{OH}		4.6		V
$V_{IH(D)}$ High-level dynamic input voltage		3.5		V
$V_{IL(D)}$ Low-level dynamic input voltage			1.5	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1 \text{ MHz}$	9	pF

PARAMETER MEASUREMENT INFORMATION



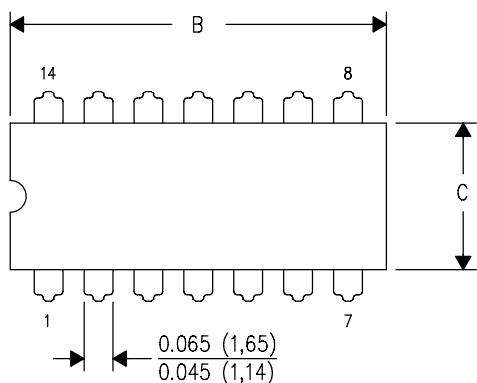
- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r \leq 3$ ns, $t_f \leq 3$ ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

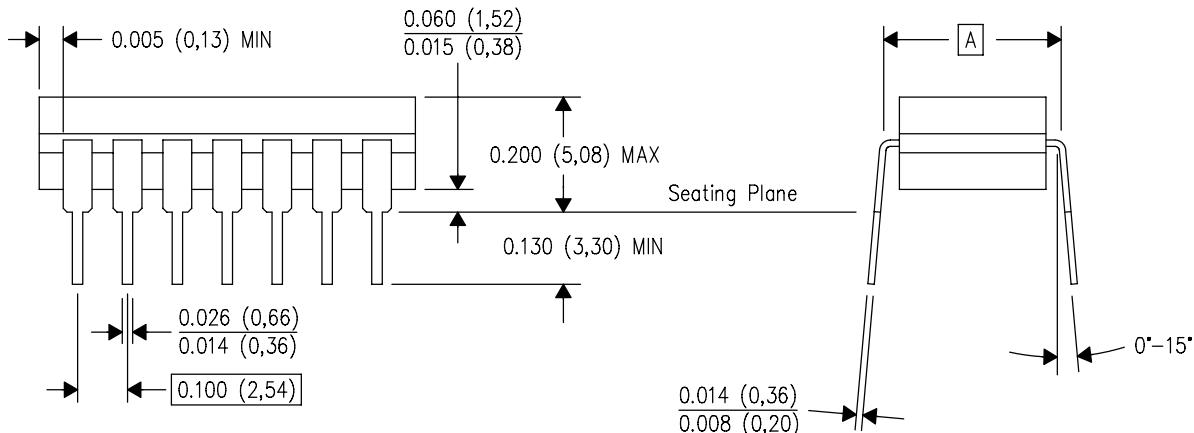
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS **\nDIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

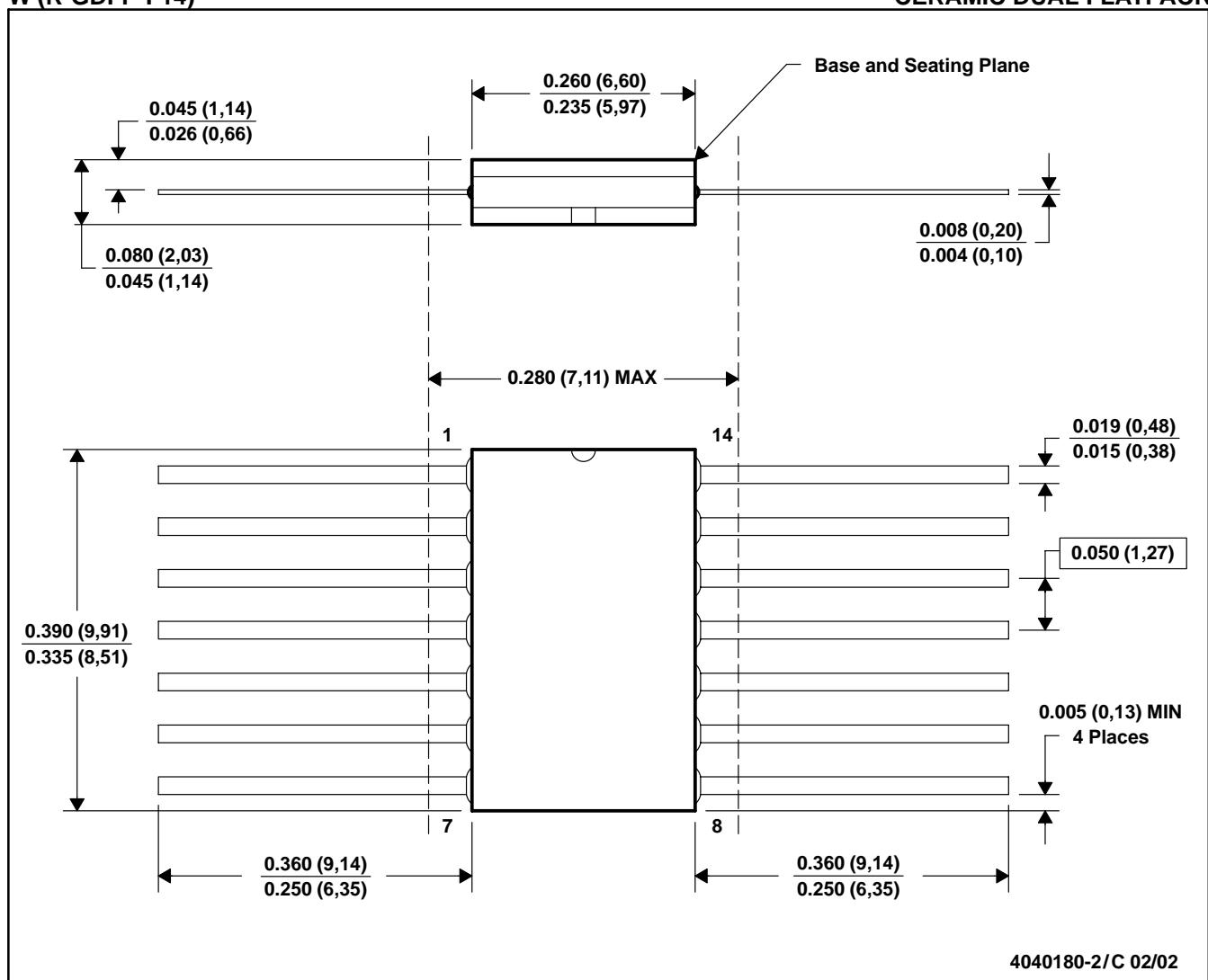


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

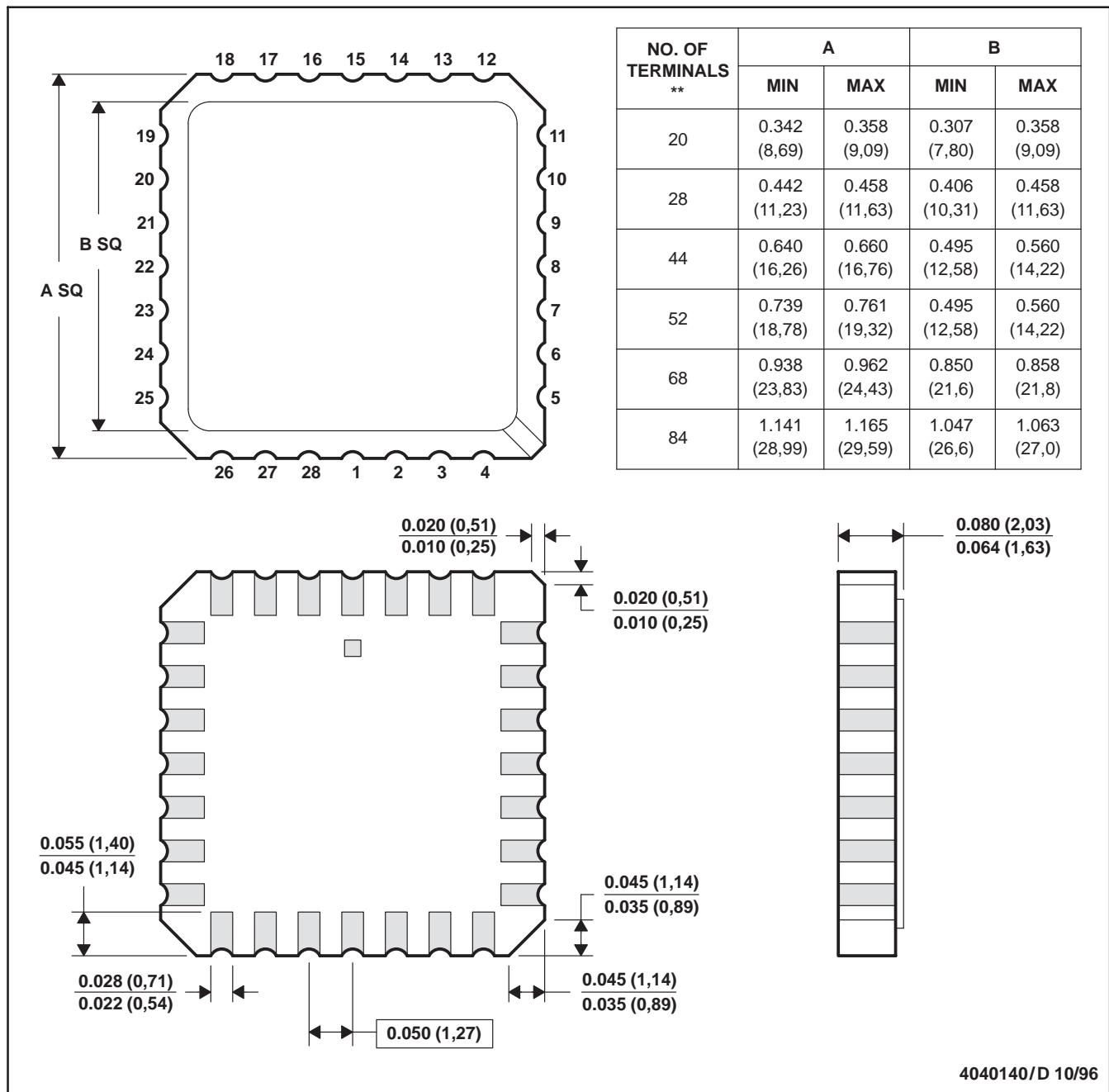


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only.
 E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. The terminals are gold plated.

E. Falls within JEDEC MS-004

4040140/D 10/96

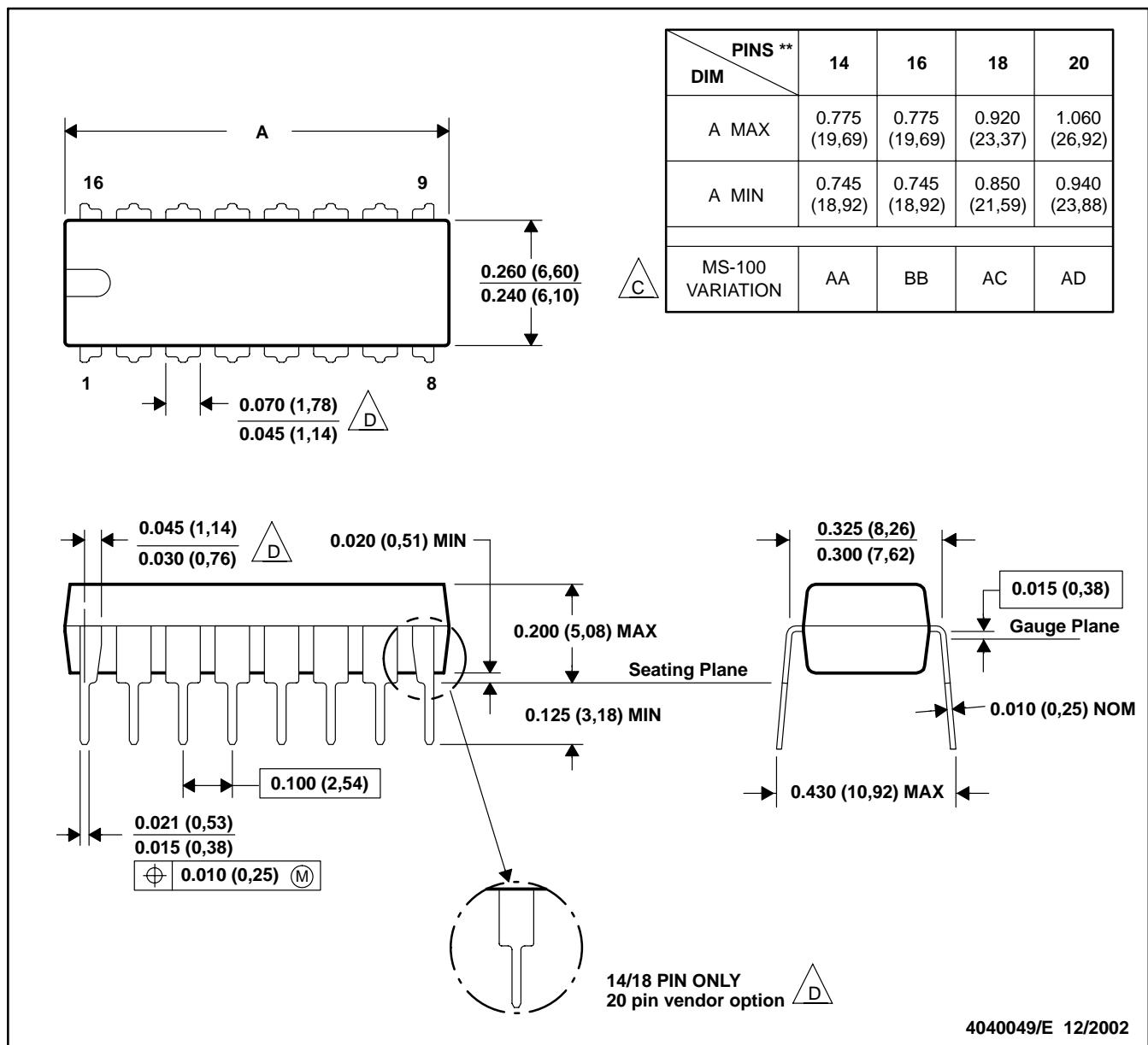
MECHANICAL

MPDI002C – JANUARY 1995 – REVISED DECEMBER 20002

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

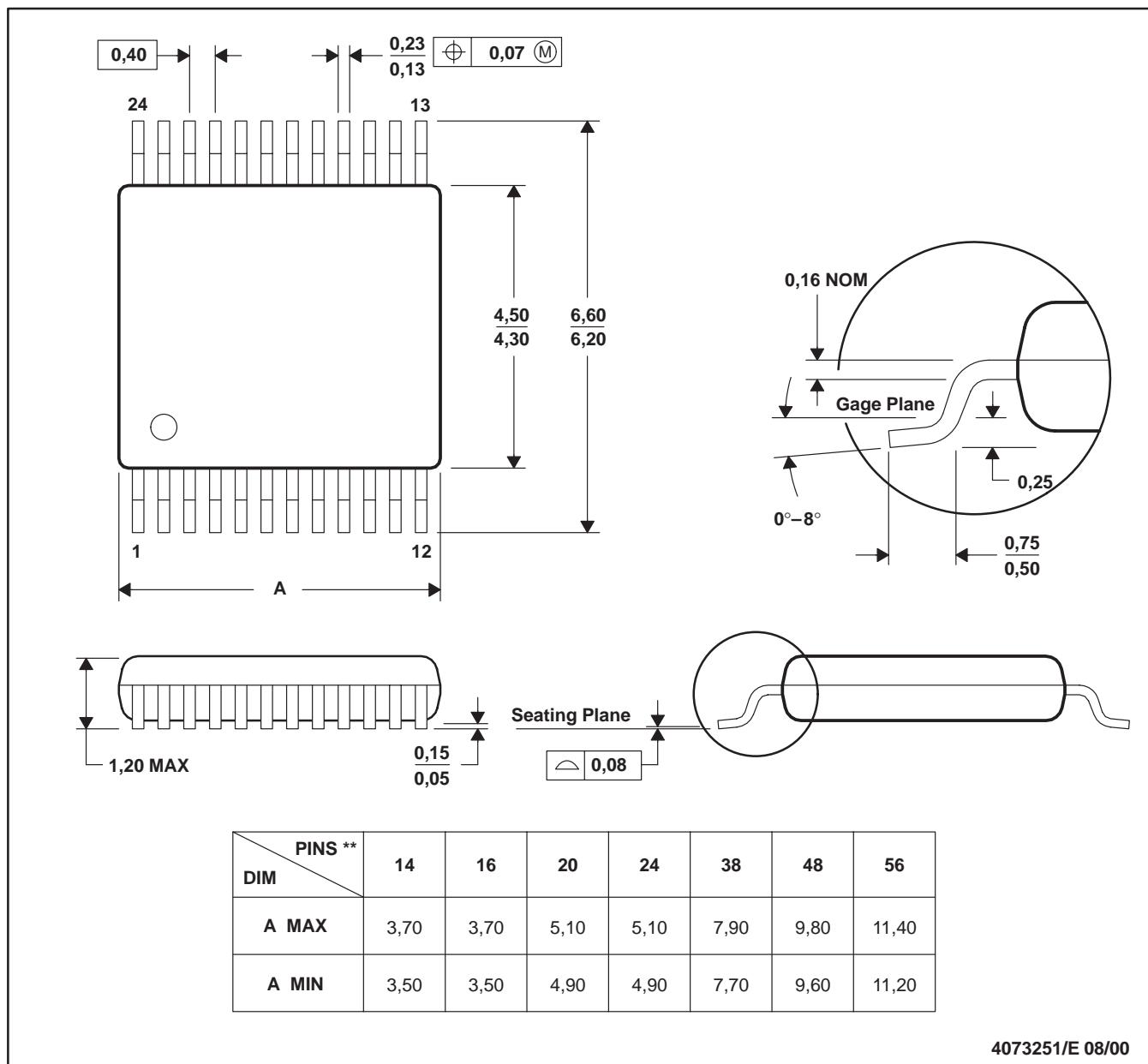
C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

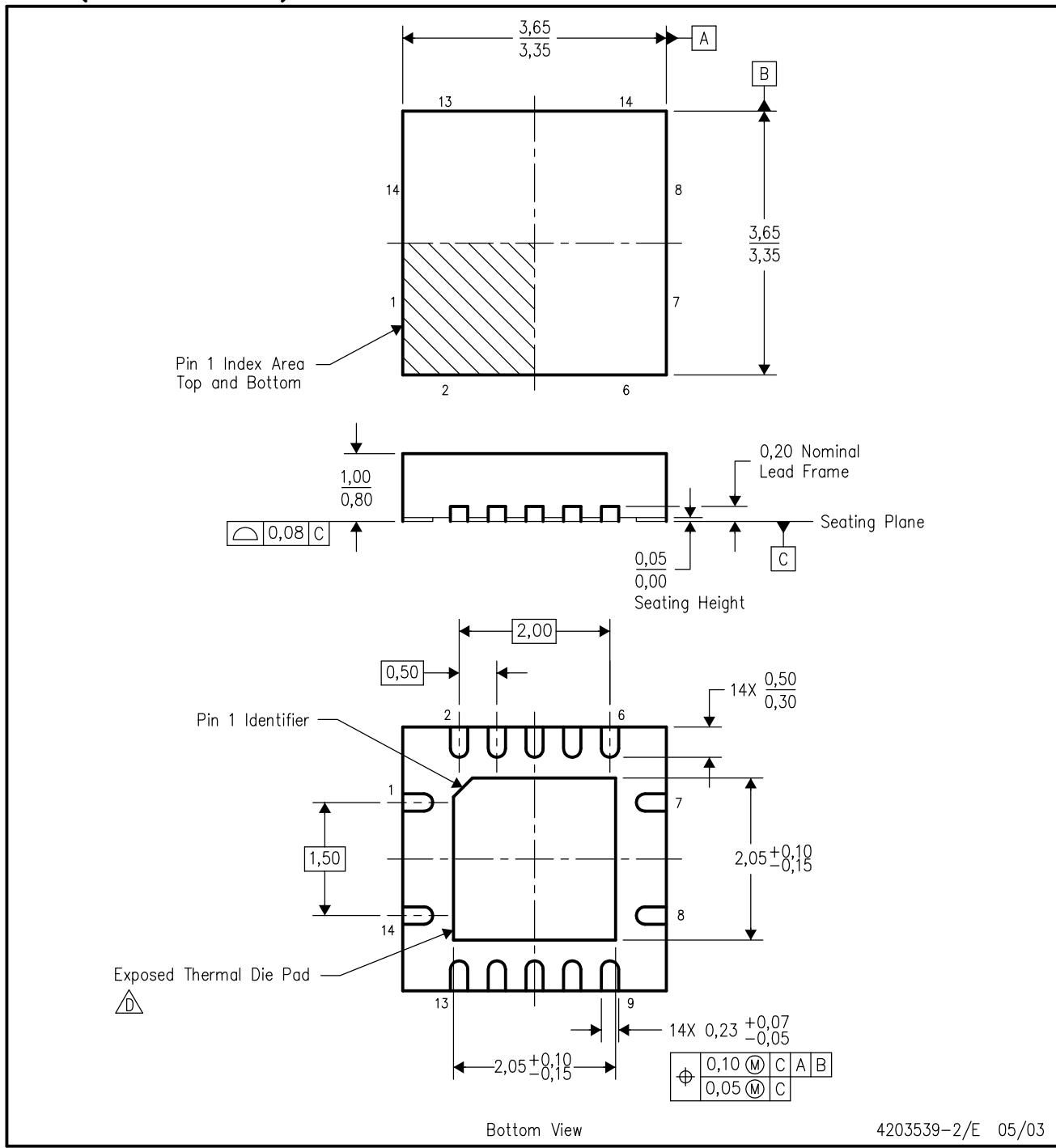
24 PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 - D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

RGY (S-PQFP-N14)

PLASTIC QUAD FLATPACK



Bottom View

4203539-2/E 05/03

NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. QFN (Quad Flatpack No-Lead) package configuration.

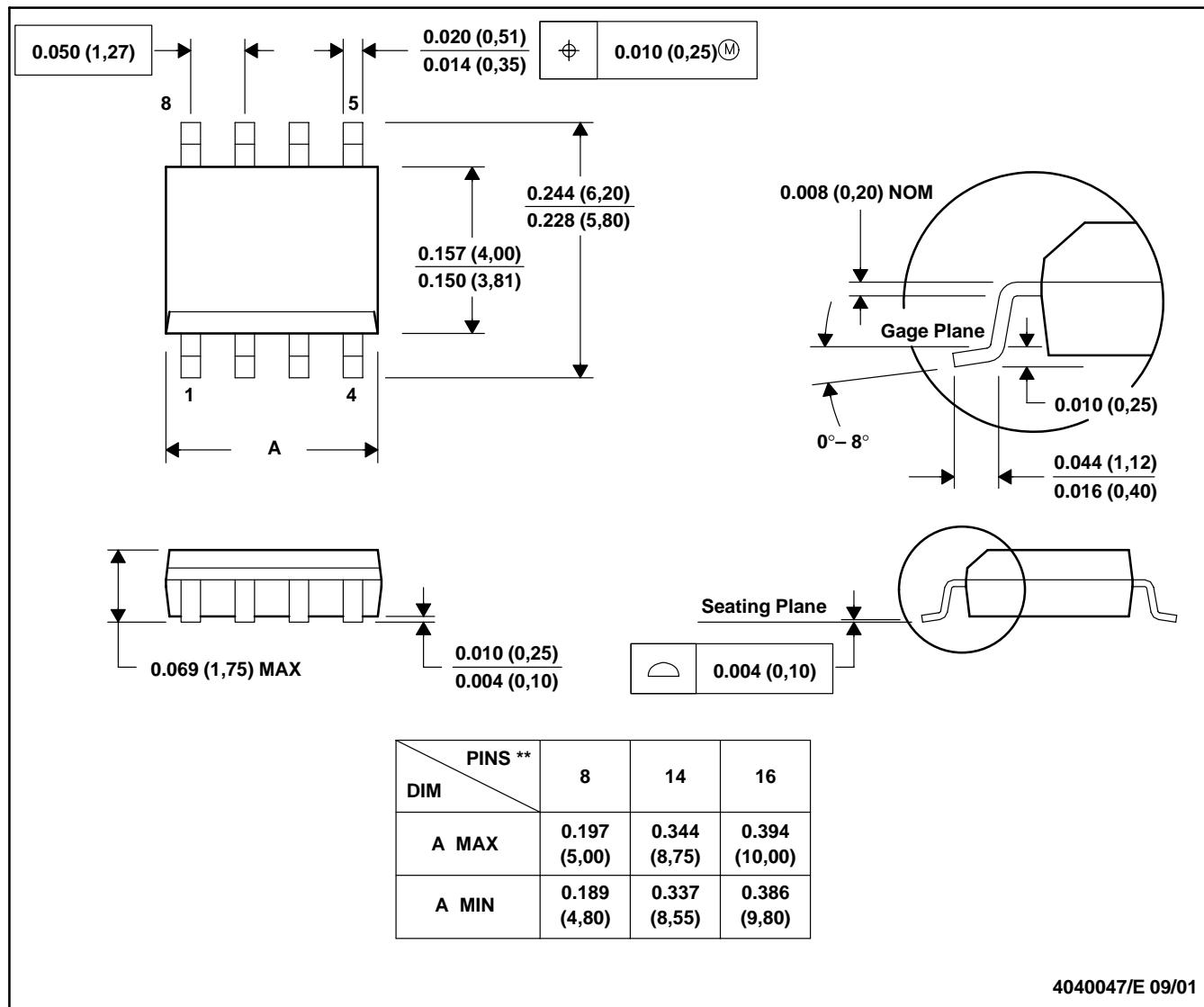
D. The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.

E. Package complies to JEDEC MO-241 variation BA.

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



4040047/E 09/01

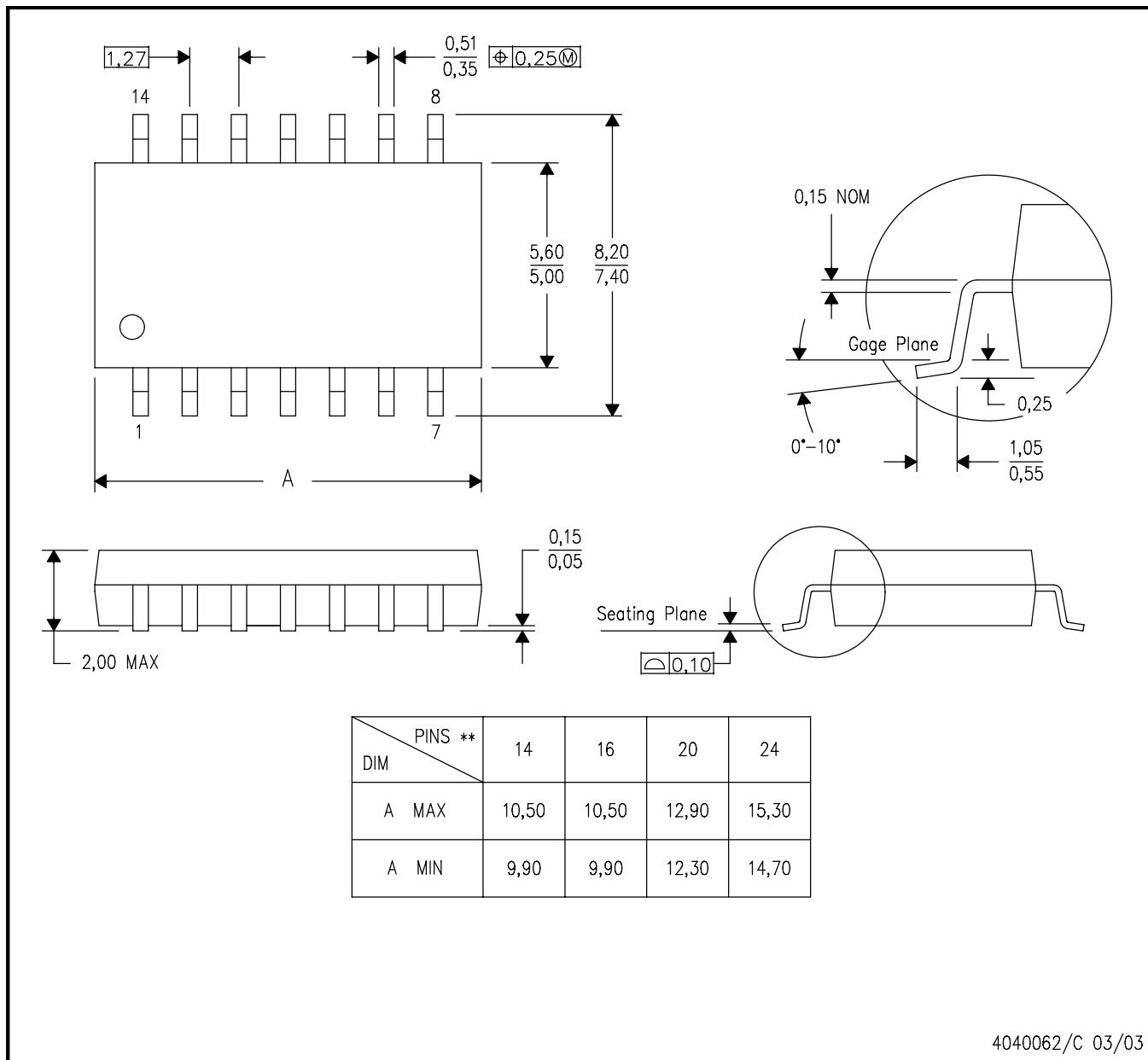
- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0.15).
 D. Falls within JEDEC MS-012

MECHANICAL DATA

NS (R-PDSO-G)**

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



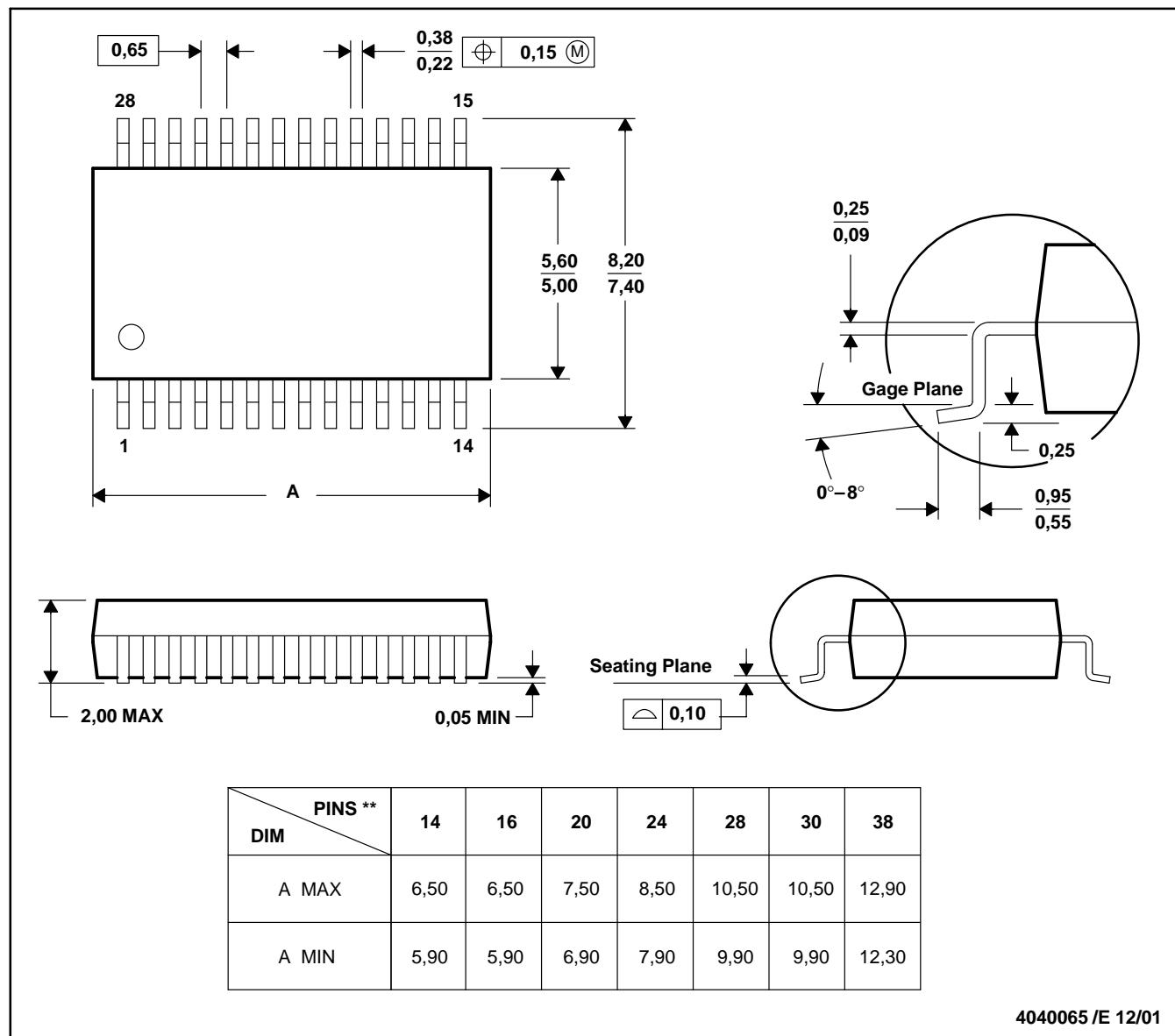
- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

4040062/C 03/03

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN

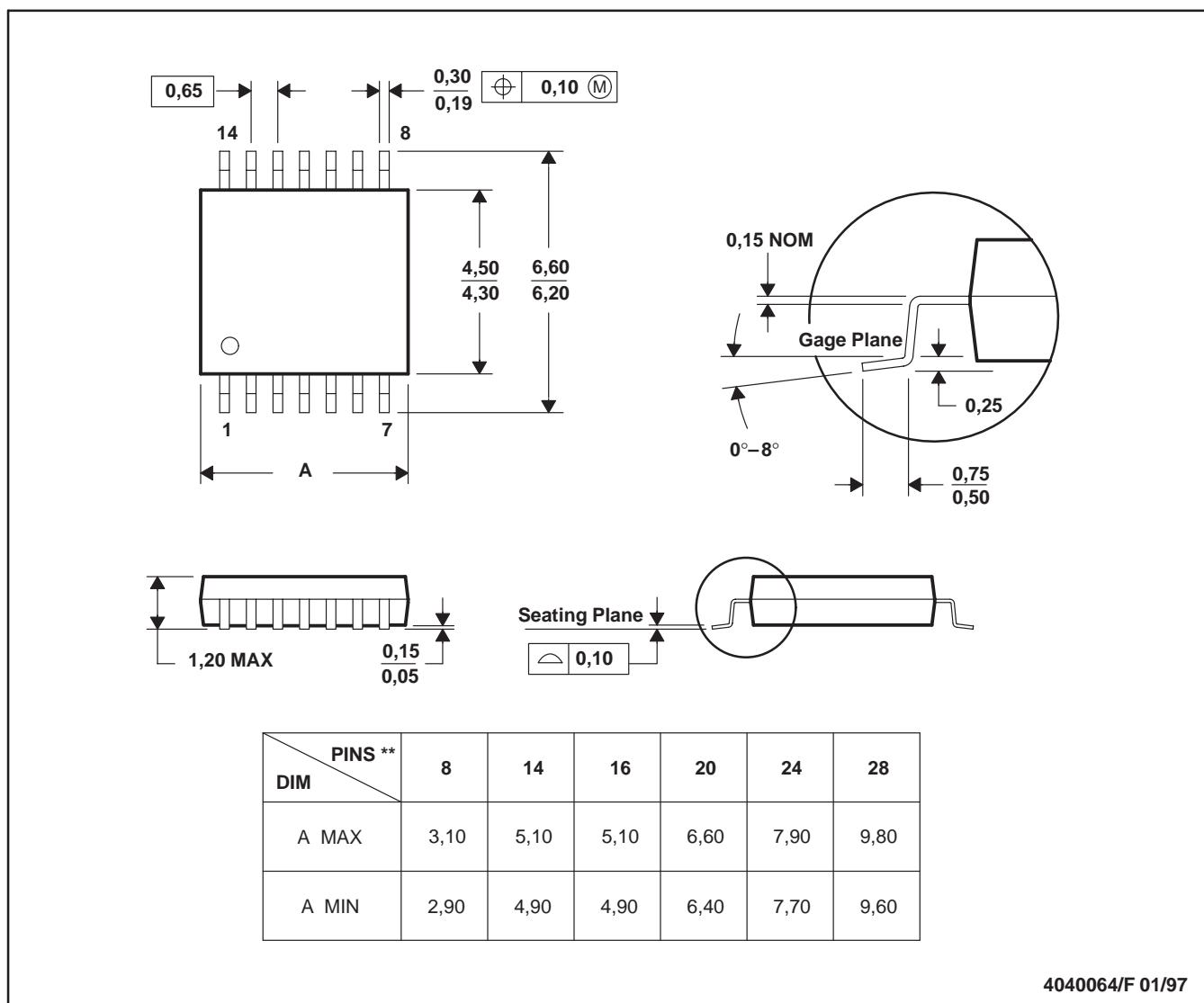


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - Falls within JEDEC MO-153

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